

UniOhm

C O N F I D E N T I A L D O C U M E N T

SPECIFICATION FOR APPROVAL

SEMIC TRADE S.R.O

Description: Thick Film Chip Resistor Array (Lead Free)

Uniohm Part no.:

4D03WGxxxxxT5E (RMC 1/16W (4D03) +/-1%, +/-5% T/R-5,000)

Approved by

Parts corresponding to RoHS Compliant: 2005-Apr.-1

Approved	Checked	Prepared
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Issue Date: 2017/11/10

[illegible]

1. Scope:

This specification for approval relates to Thick Film Chip Resistor Array (Lead Free) manufactured by UniOhm 's specifications.

2. Type designation:

The type designation shall be in the following form:

	Type	Power Rating	Resistance tolerance	Nominal Resistance
Ex.	RMC 4D03	0.0625W (1/16W)	F,J	10Ω

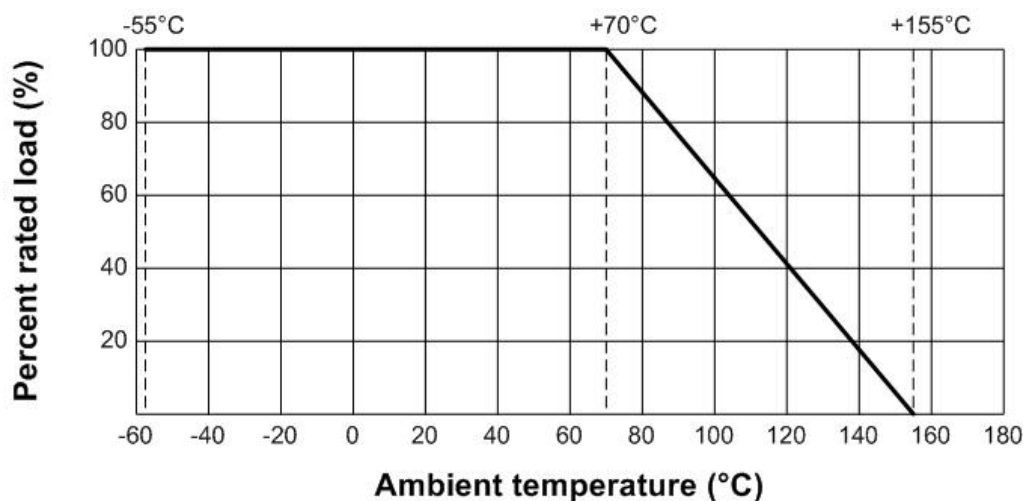
3. Ratings:

Type	RMC 4D03 (8Pin4R)
Power Rating	0.0625W at 70°C
Max. Working Voltage	50 V
Max. Overload Voltage	100 V
Dielectric Withstanding Voltage	300 V
Temperature Range	-55°C ~ +155°C
Ambient Temperature	70 °C

3.1 Power rating:

Resistors shall have a power rating based on continuous load operation at an ambient temperature of 70 °C . For temperature in excess of 70 °C , The load shall be derate as shown in figure 1.

Figure 1

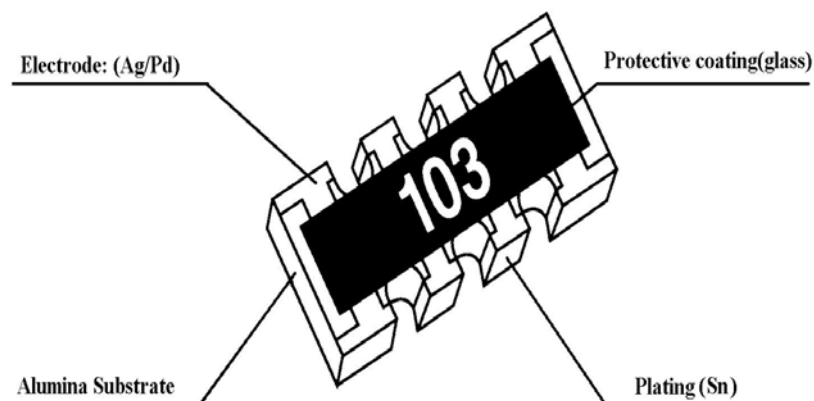


3.2 Nominal Resistance

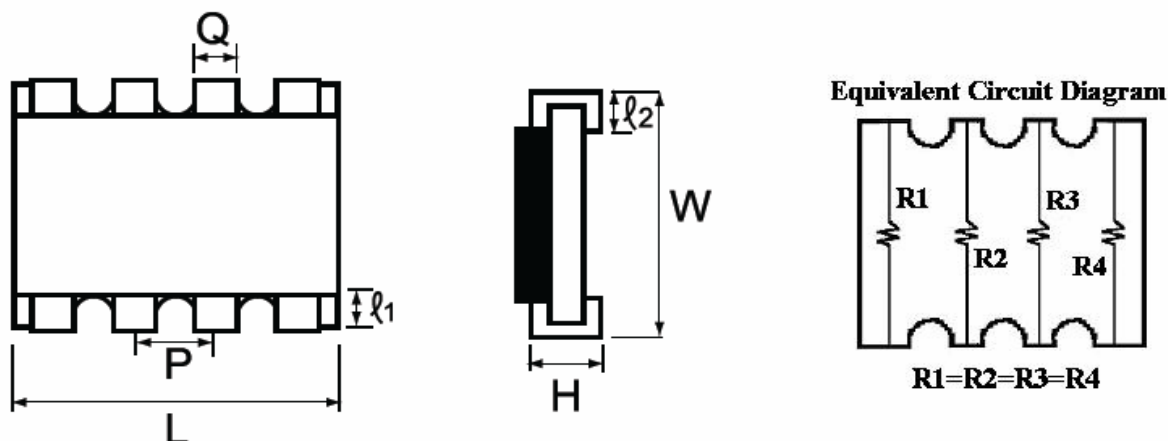
Effective figures of nominal resistance shall be in accordance with E-24 and E-96 series E-96 series for 1 % and E-24 series for 2 % and 5 %

Thick Film Chip Resistor Array (Lead Free)

4. Construction :



5. Power rating and dimensions



Dimension :

Type	Dimension (mm)						
	$L \pm 0.20$	$W \pm 0.20$	$H \pm 0.10$	$l1 \pm 0.15$	$l2 \pm 0.15$	$P \pm 0.10$	$Q \pm 0.15$
RMC 4D03	3.20	1.60	0.50	0.30	0.40	0.8	0.50

Power Rating :

Type	Power Rating at 70 °C	Tolerance %	Resistance Range	Standard Resistance values
RMC 4D03	0.0625 W (1/16W)	± 1	10 Ω ~ 1M Ω	E-96
		± 5	1 Ω ~ 1M Ω	E-24

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6. Marking :

6.1 Resistors

A. Marking for E-96 series in 4D03 size : 4 Digits

*The first 3 digits are significant figures of resistance and the 4th digit denoted number of zeros.

Ex.	<table border="1" style="display: inline-table; vertical-align: middle;"><tr><td style="width: 30px; height: 30px;"></td><td style="width: 100px; height: 30px; text-align: center;">1003</td><td style="width: 30px; height: 30px;"></td></tr></table>		1003		100K Ω
	1003				

*For ohmic values below 10 Ω , letter "R" is for decimal point.

Ex.	<table border="1" style="display: inline-table; vertical-align: middle;"><tr><td style="width: 30px; height: 30px;"></td><td style="width: 100px; height: 30px; text-align: center;">1R80</td><td style="width: 30px; height: 30px;"></td></tr></table>		1R80		1.8 Ω
	1R80				

B. Marking for E-24 series in 4D03 size : 3 Digits

*The first 2 digits are significant figures of resistance and the 3rd digit denoted number of zeros.

Ex.	<table border="1" style="display: inline-table; vertical-align: middle;"><tr><td style="width: 30px; height: 30px;"></td><td style="width: 100px; height: 30px; text-align: center;">103</td><td style="width: 30px; height: 30px;"></td></tr></table>		103		10K Ω
	103				

*For ohmic values below 10 Ω , letter "R" is for decimal point.


Ex.	<table border="1" style="display: inline-table; vertical-align: middle;"><tr><td style="width: 30px; height: 30px;"></td><td style="width: 100px; height: 30px; text-align: center;">R68</td><td style="width: 30px; height: 30px;"></td></tr></table>		R68		0.68 Ω
	R68				

6.2 Labels

Label shall be marked with the following item :

- A. Nominal Resistance and Resistance Tolerance
- B. Power Rating and Size
- C. Quantity
- D. Part No.
- E. P.O.No.
- F. Lot No.

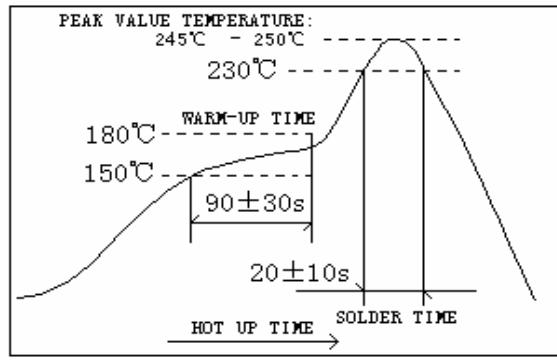
Ex.

UniOhm		
CHIP RESISTOR		
RESISTANCE: 10	Ω	$\pm 5\%$
WATTAGE: 1/16W	SIZE: 4D03	
QUANTITY: 5,000	PCS	Pb-Free
PART NO.:		
P.O.NO.:		
LOT NO. :	6050008	4D03WGJ0100T5E
		

Remark : Label is 10R, value is 10 Ω , marking is 100

Thick Film Chip Resistor Array (Lead Free)

7. Performance specification :

Characteristics	Limits	Test Methods (JIS C 5201-1)
Insulation resistance	1,000 MΩ or more	4.6 Apply 500V DC between protective coating and termination for 1 min, then measure
Dielectric withstanding voltage	No evidence of flashover mechanical damage, arcing or insulation break down	4.7 Apply 500V AC between protective coating and termination for 1 minute
Temperature coefficient	$<10\Omega : \pm 400 \text{ PPM}/^{\circ}\text{C}$ $\geq 10\Omega : \pm 200 \text{ PPM}/^{\circ}\text{C}$	4.8 Natural resistance change per temp. degree centigrade. $\frac{R_2 - R_1}{R_1(t_2 - t_1)} \times 10^6 \quad (\text{PPM}/^{\circ}\text{C})$ R1: Resistance value at room temperature (t1) R2: Resistance value at room temp. plus 100 °C (t2)
Short time overload	Resistance change rate is $\pm (2.0\% + 0.1\Omega)$ Max.	4.13 Permanent resistance change after the application of a potential of 2.5 times RCWV for 5 seconds
Solderability	95 % coverage Min.	Wave Solder: Test temperature of solder: 245°C \pm 3°C dipping time in solder : 2-3 seconds.
	Go up tin rate bigger than half of end pole.	Reflow: 
Soldering Heat	Resistance change rate is: $\pm (1\% + 0.05\Omega)$ Max.	4.18 Dip the resistor into a solder bath having a temperature of 260°C \pm 3°C and hold it for 10 \pm 1 seconds.

Thick Film Chip Resistor Array (Lead Free)

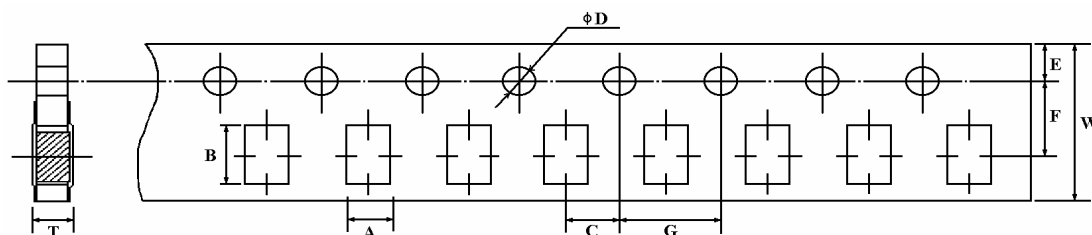
7. Performance specification :

Characteristics	Limits	Test Methods (JIS C 5201-1)		
Temperature cycling	Resistance change rate is $\pm (1.0\% + 0.05\Omega)$ Max.	4.19 Resistance change after continuous 5 cycles for duty cycle specified below :		
		Step	Temperature	Time
		1	$-55^{\circ}\text{C} \pm 3^{\circ}\text{C}$	30 mins
		2	Room temp.	10~15 mins
		3	$+155^{\circ}\text{C} \pm 2^{\circ}\text{C}$	30 mins
		4	Room temp.	10~15 mins
Load life in humidity	Resistance change rate is $\pm (3.0\% + 0.1\Omega)$ Max.	7.9 Resistance change after 1,000 hours (1.5 hours "on", 0.5 hour "off") at RCWV in a humidity chamber controlled at $40^{\circ}\text{C} \pm 2^{\circ}\text{C}$ and 90 to 95 % relative humidity		
Load Life	Resistance change rate is $\pm (3.0\% + 0.1\Omega)$ Max.	4.25.1 Permanent resistance change after 1,000 hours operating at RCWV, with duty cycle of (1.5 hours"on", 0.5 hour"off") at $70^{\circ}\text{C} \pm 2^{\circ}\text{C}$ ambient		
Terminal bending	Resistance change rate is $\pm (1.0\% + 0.05\Omega)$ Max.	4.33 Twist of Test Board : Y/X = 3/90 mm for 60 seconds		

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8. Packing specification :

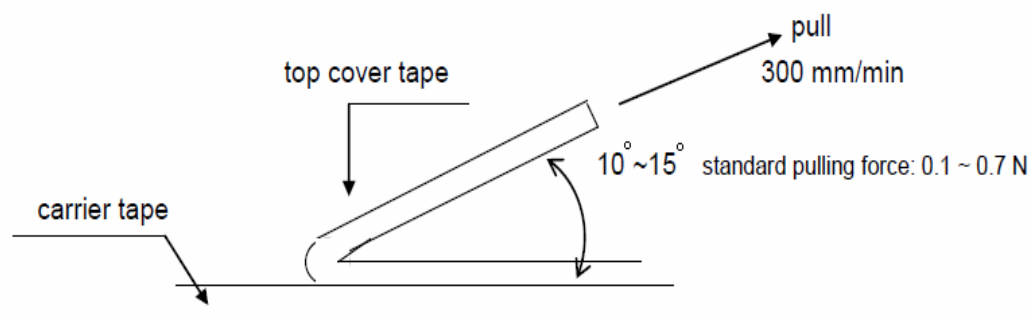
* Taping Dimension (mm)



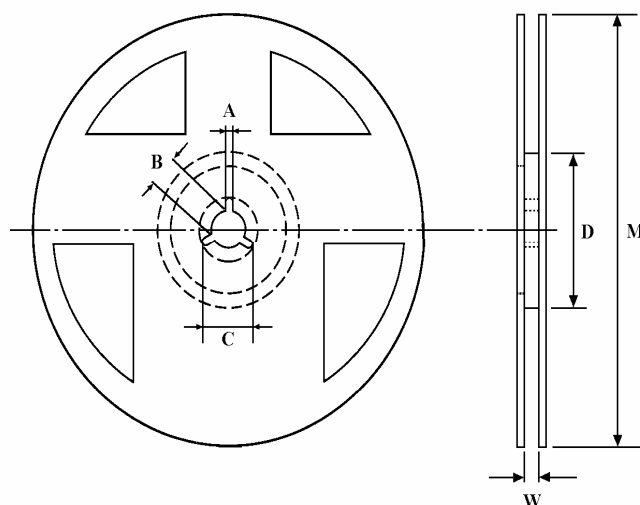
Type	A ± 0.2	B ± 0.2	C ± 0.05	$\phi D +0.1$ - 0	E ± 0.1	F ± 0.05	G ± 0.1	W ± 0.2	T ± 0.1	T ± 0.1
RMC 4D03	2.0	3.6	2.0	1.5	1.75	3.5	4.0	8.0	0.83	1.0

* Peeling Strength of Top Cover Tape

Test Condition: 0.1 to 0.7 N at a peel-off speed of 300 mm / min.



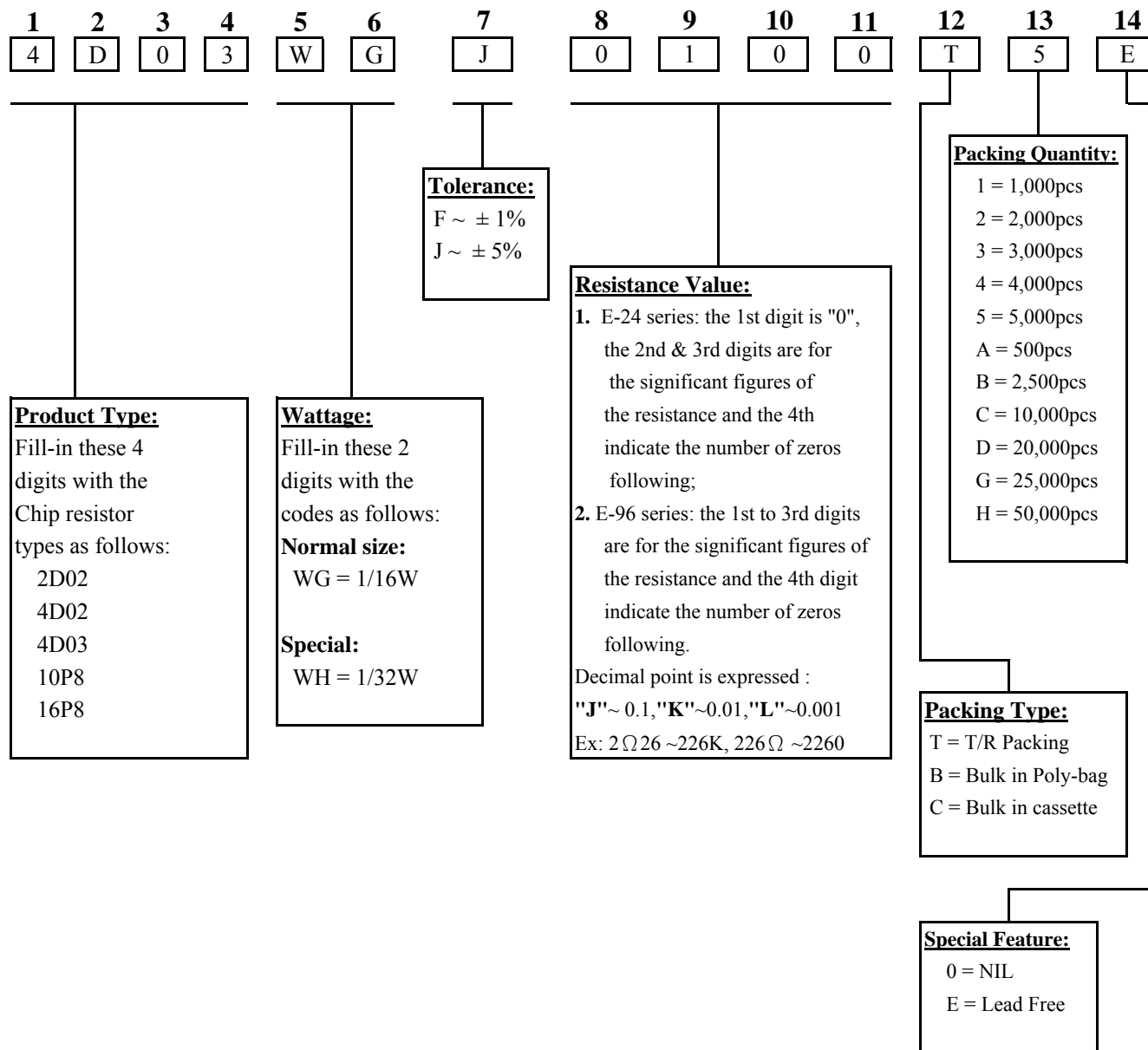
* Reel Dimension (mm)



Type	Quantity Per Reel	A ± 0.5	B ± 0.5	C ± 0.5	D ± 1	M ± 2	W ± 1
RMC 4D03	5,000 pcs.	2	13	21	60	178	10

Part Number System

Explanation of Part Number System (Thick Film Chip Resistor Array (Lead Free))



Sample : RMC 1/16W (4D03) +/- 5% 10Ω T/R-5,000 → 4D03WGF0100T5E
 RMC 1/16W (4D03) +/- 1% 10Ω T/R-5,000 → 4D03WGF100JT5E

Thick Film Chip Resistor Array (Lead Free)

Environment Related Substance

This product complies to EU RoHS directive, EU PAHs directive, EU PFOS directive and Halogen free.

Ozone layer depleting substances.

Ozone depleting substances are not used in our manufacturing process of this product.

This product is not manufactured using Chloro fluorocarbons (CFCs), Hydrochlorofluorocarbons (HCFCs), Hydrobromofluorocarbons (HBFCs) or other ozone depleting substances in any phase of the manufacturing process.

Storage Condition

The performance of these products, including the solderability, is guaranteed for a year from the date of arrival at your company, provided that they remain packed as they were when delivered and stored at a temperature of $25^{\circ}\text{C} \pm 10^{\circ}\text{C}$ and a relative humidity of $60\%\text{RH} \pm 10\%\text{RH}$, chemical and dust free atmosphere

Even within the above guarantee periods, do not store these products in the following conditions. Otherwise, their electrical performance and/or solderability may be deteriorated, and the packaging materials (e.g. taping materials) may be deformed or deteriorated, resulting in mounting failures.

1. In salty air or in air with a high concentration of corrosive gas, such as Cl_2 , H_2S , NH_3 , SO_2 , or NO_2
2. In direct sunlight